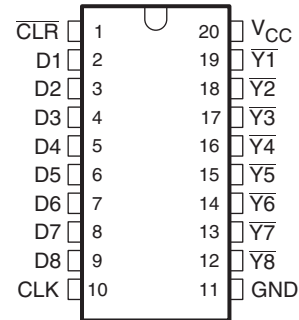


## 8-BIT OPEN-COLLECTOR SINK DRIVER WITH LATCH

### FEATURES

- LBC3S (Lin BiCMOS) Process
- High Voltage Output ( $V_{OUT} = 24\text{ V}$ )
- Output Current ( $I_{OL}\text{ Max} = 40\text{ mA}$ )
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged Device Model (C101)

N OR PW PACKAGE  
(TOP VIEW)



### DESCRIPTION

The TLC59212 is an 8-bit open-collector driver with latch designed for 5-V  $V_{CC}$  operation.

These circuits are positive-edge-triggered D-type flip-flops with a direct clear ( $\overline{\text{CLR}}$ ) input. Information at the data (D) input meeting the setup time requirements is transferred to the  $\overline{\text{Y}}$  output on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D-input has no effect at the output.

The TLC59212 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

### ORDERING INFORMATION<sup>(1)</sup>

$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
$-40^{\circ}\text{C}$ to $85^{\circ}\text{C}$	PDIP – N	Reel of 1000	TLC59212IN	Y59212
	TSSOP – PW	Reel of 2000	TLC59212IPWR	Y59212

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

(2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

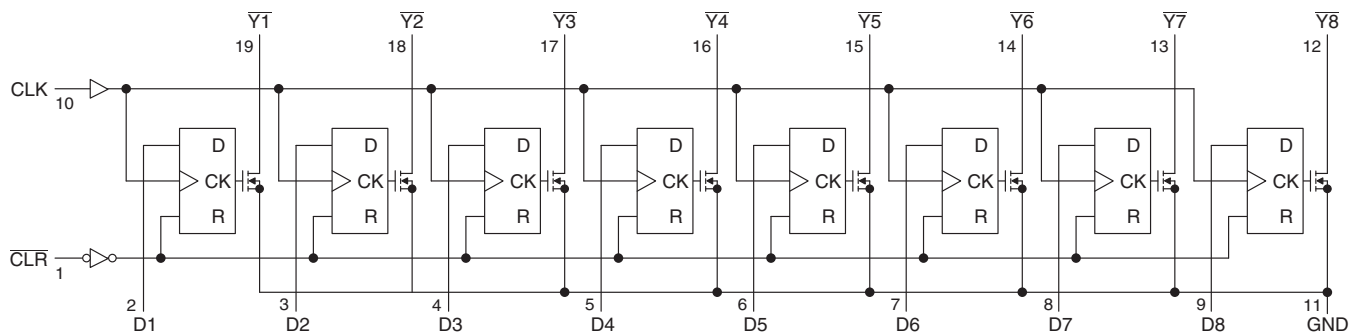
### FUNCTION TABLE (EACH LATCH)<sup>(1)</sup>

INPUTS			OUTPUT $\overline{\text{Y}}$
$\overline{\text{CLR}}$	CLK	D	
L	X	X	H*
H	↑	L	H*
H	↑	H	L
H	L	X	$\text{Y}_0$
H	↓	X	$\text{Y}_0$

- (1) L: Low-level  
H: High-level  
H\*: with pullup resistor  
X: Irrelevant  
↑: Rising edge  
↓: Falling edge  
Z: High-impedance (OFF)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**LOGIC SYMBOL<sup>(1)</sup>**

(1) This symbol is in accordance with ANSI/IEEE Standard 91-1984 and IEC Publication 617-12.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
D	Input voltage range	-0.5	7	V
$V_O$	Output voltage range	-0.5	30	V
$I_O$	Output current range		40	mA
$I_{IK}$	Input clamp current		-20	mA
$\theta_{JA}$	Package thermal impedance <sup>(2)</sup>		69	°C/W
	N package		83	
$T_A$	Operating free-air temperature range	-40	85	°C
$T_{stg}$	Storage temperature range	-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The package thermal impedance is calculated in accordance with JESD 51-7.

**RECOMMENDED OPERATING CONDITIONS**

$V_{CC} = 4.5\text{ V to }5.5\text{ V}$

	CONDITIONS	MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} \times 0.7$	$V_{CC}$	V
$V_{IL}$	Low-level input voltage	0	$V_{CC} \times 0.3$	V
$V_O$	Output voltage	0	24	V
$I_O$	Output current	0	40	mA
$T_A$	Operating free-air temperature	-40	85	°C

## ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{th}$	Positive-going input threshold	D, $\overline{CLR}$ , CLK			3.5	V
$V_{tl}$	Negative-going input threshold	D, $\overline{CLR}$ , CLK	1.5			V
$V_t$	Hysteresis	D, $\overline{CLR}$ , CLK	0.5		2	V
$V_{O(off)}$	Output tr sustain voltage	$I_{ce} = 1$ mA	24			V
$I_{OZ}$	Output tr leakage current	$V_O = 24$ V		0	5	$\mu$ A
$I_{IH}$	High-level input current	$V_{CC} = 5.5$ V, $V_I = 5.5$ V		0	1	$\mu$ A
$I_{IL}$	Low-level input current	$V_{CC} = 5.5$ V, $V_I = 0$ V		0	–1	$\mu$ A
$I_{off}$	Leakage current	$V_I = 0$ to 5 V, $V_O = 0$ to 30 V, $V_{CC} = 0$		0	5	$\mu$ A
$I_{CC}$	Supply current	$V_I = 0$ to 5 V, $V_O = 0$ to 30 V, $V_{CC} = 0$	Output = all OFF		0	5
			Output = all ON		8	20
$V_{OL}$	Low-level output voltage	$V_{CC} = 4.5$ V, $I_O = 40$ mA		0.32	0.55	V
$r_{ON}$	ON-state resistance	$V_{CC} = 4.5$ V, $I_O = 10$ mA		8	13	$\Omega$
$C_i$	Input capacitance	$V_I = V_{CC}$ or GND		5		pF

## SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted), see [Figure 1](#)

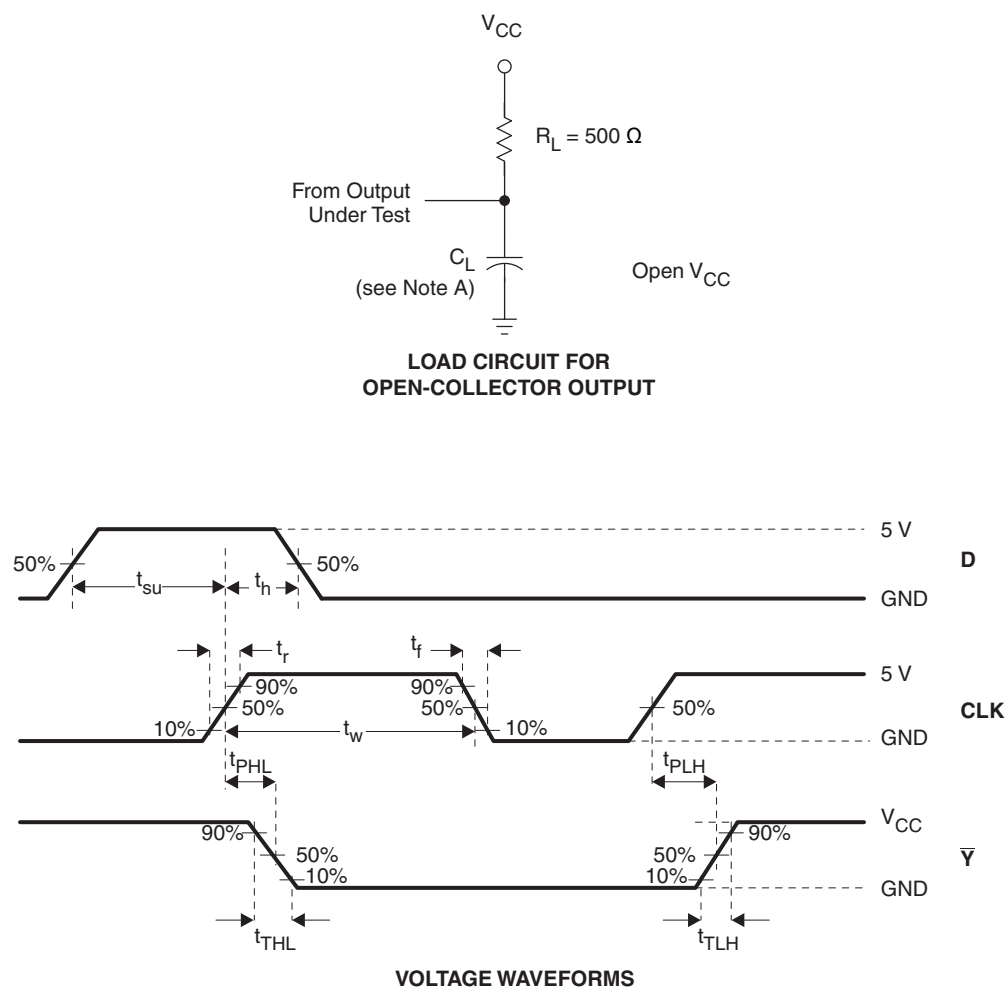
PARAMETER	TEST CONDITIONS	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$t_{TLH}$	Output = low to high	$C_L = 50$ pF, $R_L = 500$ $\Omega$		60	185		185	ns
$t_{THL}$	Output = high to low	$C_L = 50$ pF, $R_L = 500$ $\Omega$		10	185		185	ns
$t_{PLH}$	Output = low to high	$C_L = 50$ pF, $R_L = 500$ $\Omega$		70	210		250	ns
$t_{PHL}$	Output = high to low	$C_L = 50$ pF, $R_L = 500$ $\Omega$		45	210		250	ns
$t_{PHLR}$	$\overline{CLR}$ - $\overline{Y}$	$C_L = 50$ pF, $R_L = 500$ $\Omega$		70	210		250	ns

## TIMING REQUIREMENTS

over recommended operating free-air temperature range,  $V_{CC} = 4.5$  V to 5.5 V, O/C to Y (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
			MIN	MAX	
$t_{su}$	Setup time	CLK	$V_{DD} = 4.5$ V to 5.5 V	5	ns
$t_h$	Hold time	CLK	$V_{DD} = 4.5$ V to 5.5 V	15	ns
$t_w$	Pulse width	CLK, $\overline{CLR}$	$V_{DD} = 4.5$ V to 5.5 V	20	ns

## PARAMETER MEASUREMENT INFORMATION



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 3 \text{ ns}$ , and  $t_f \leq 3 \text{ ns}$ .
- D. The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 1. Test Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TLC59212IN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC59212IPWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLC59212IPWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLC59212IPWR	TSSOP	PW	20	2000	367.0	367.0	38.0

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

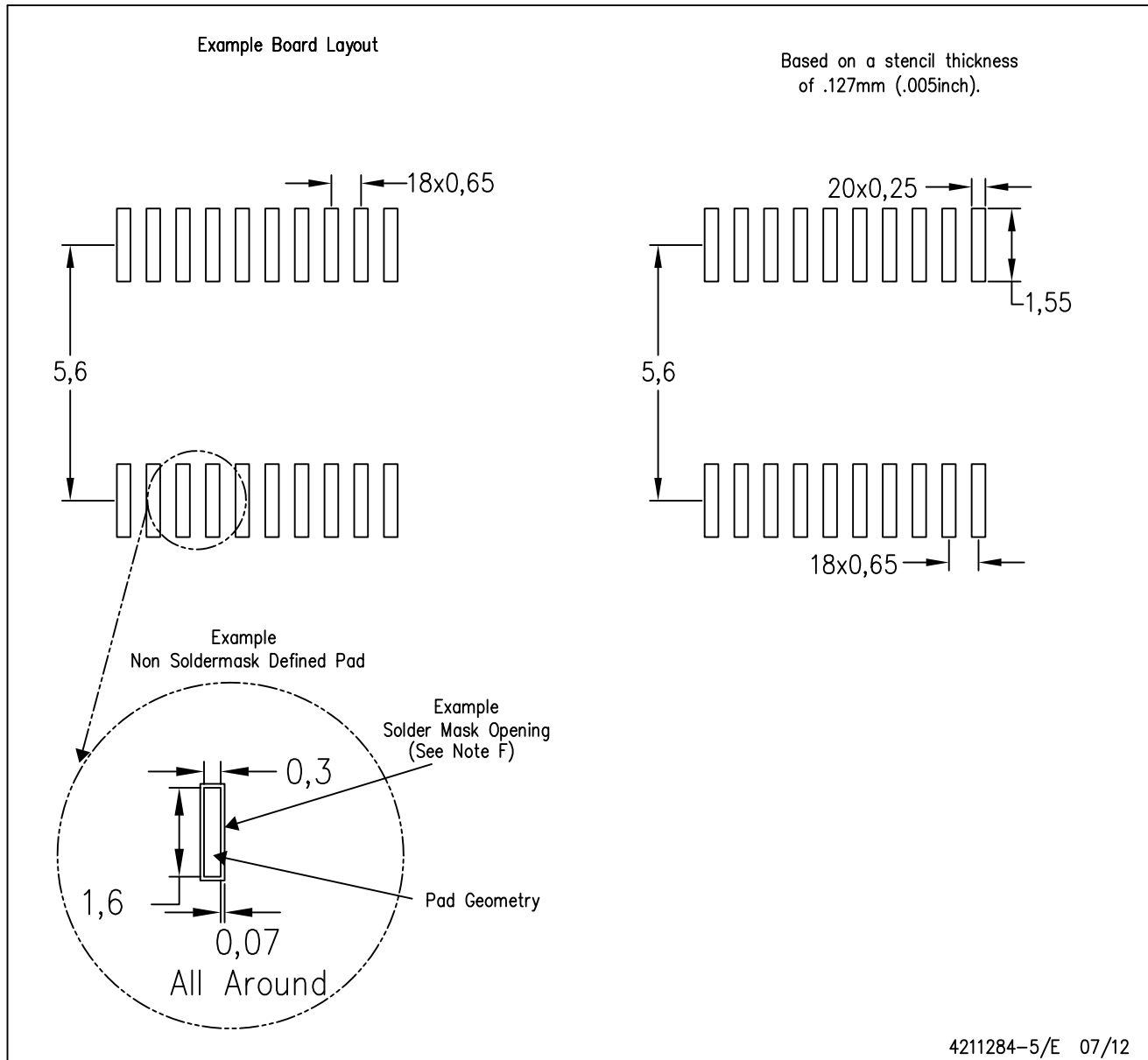


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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